

1. Features

- Typical 1dB bandwidth of 33.6 MHz
- High attenuation
- Single Ended Operation
- Surface Mounted Package (SMD)

RoHS Compliant

Tested by SGS Testing Korea

2. Electrical Specifications

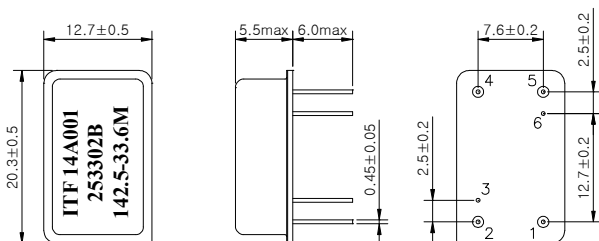
Source and Load Impedance = 50Ω

Operating Temperature : -30 ~ +70 °C		Minimum	Typical	Maximum
Center Frequency (fo)	MHz	-	142.5	-
Insertion Loss	dB	-	25.0	27.0
1dB Bandwidth	MHz	33.4	33.63	-
3dB Bandwidth	MHz	-	33.98	-
40dB Bandwidth	MHz	-	35.55	35.9
Amplitude Ripple (fo ± 16.0 MHz)	dB	-	0.65	1.2
Group Delay Variation (fo ± 16.0 MHz)	nsec	-	30	60
Absolute Delay	usec	-	1.78	-
Ultimate Rejection	dB	48	53	-
Temperature Coefficient of Frequency	ppm/°C	-	-72	-
Relative Attenuation (fo ± 16.0MHz)±2MHz	dB	40	52	-

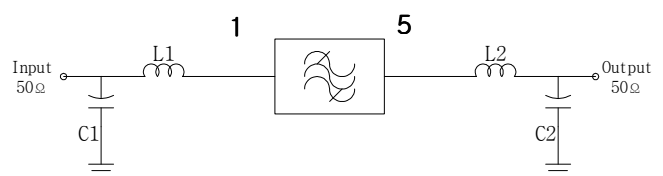
Room Temperature : +25 °C		Minimum	Typical	Maximum
Insertion Loss	dB	-	25.0	27.0
Amplitude Ripple (fo ± 16.56 MHz)	dB	-	0.65	1.2
Group Delay Variation (fo ± 16.56 MHz)	nsec	-	30	60

* Input POWER : +10dBm

D2012 Package Dimension



Matching Schematic



L1 = 39nH, L2 = 56nH, C1 = 4.7pF, C2 = 20pF

Pin Configuration

	1	Ground	2,4
Input	1	Ground	2,4
Output	5	Others	Ground

Dimensions shown are nominal in millimeters

Base : Fe(SPCC), Au plating over Ni plated
 Cap : Cu & Cr Alloy, Ni Plated
 Termination : Kovar, Au Plated

3. Typical Performance (at +25°C)

